



Materials Declaration

Package	LQFP
Body Size	14 X 14
LeadCount	120
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.67 E-02	28396
SiO2 Filler	86	1.79 E-01	305257
Phenol Resin	5	1.04 E-02	17748
Antimony_Sb2O3	0.4	8.34 E-04	1420
Brominated Resin	0.4	8.34 E-04	1420
Carbon Black	0.2	4.17 E-04	710

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.24 E-01	380638
Ni	3	6.97 E-03	11870
Si	0.65	1.51 E-03	2572
Mg	0.15	3.49 E-04	594

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	8.50 E-04	1447

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	9.15 E-03	15578

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	3.90 E-03	6647

Chip			
	% of Chip	Weight (g)	PPM
Si	100	1.21 E-01	205890

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.03 E-03	5152
Ag Filler	74	8.61 E-03	14662

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals	
Weight (g)	PPM
5.87 E-01	1000000

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

6/21/04





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Body Size	14 X 14
LeadCount	120
Option	Sn/Pb

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Epoxy resin	8	1.67 E-02	28396
SiO2 Filler	86	1.79 E-01	305257
Phenol Resin	5	1.04 E-02	17748
Antimony_Sb2O3	0.4	8.34 E-04	1420
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Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.24 E-01	380638
Ni	3	6.97 E-03	11870
Si	0.65	1.51 E-03	2572
Mg	0.15	3.49 E-04	594

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	8.50 E-04	1447

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	7.78 E-03	13242
Pb	15	1.37 E-03	2337

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	3.90 E-03	6647

Chip			
	% of Chip	Weight (g)	PPM
Si	100	1.21 E-01	205890

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.03 E-03	5152
Ag Filler	74	8.61 E-03	14662

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Item	PPM	Method
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Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals	
Weight (g)	PPM
5.87 E-01	1000000

STS-ST-A

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